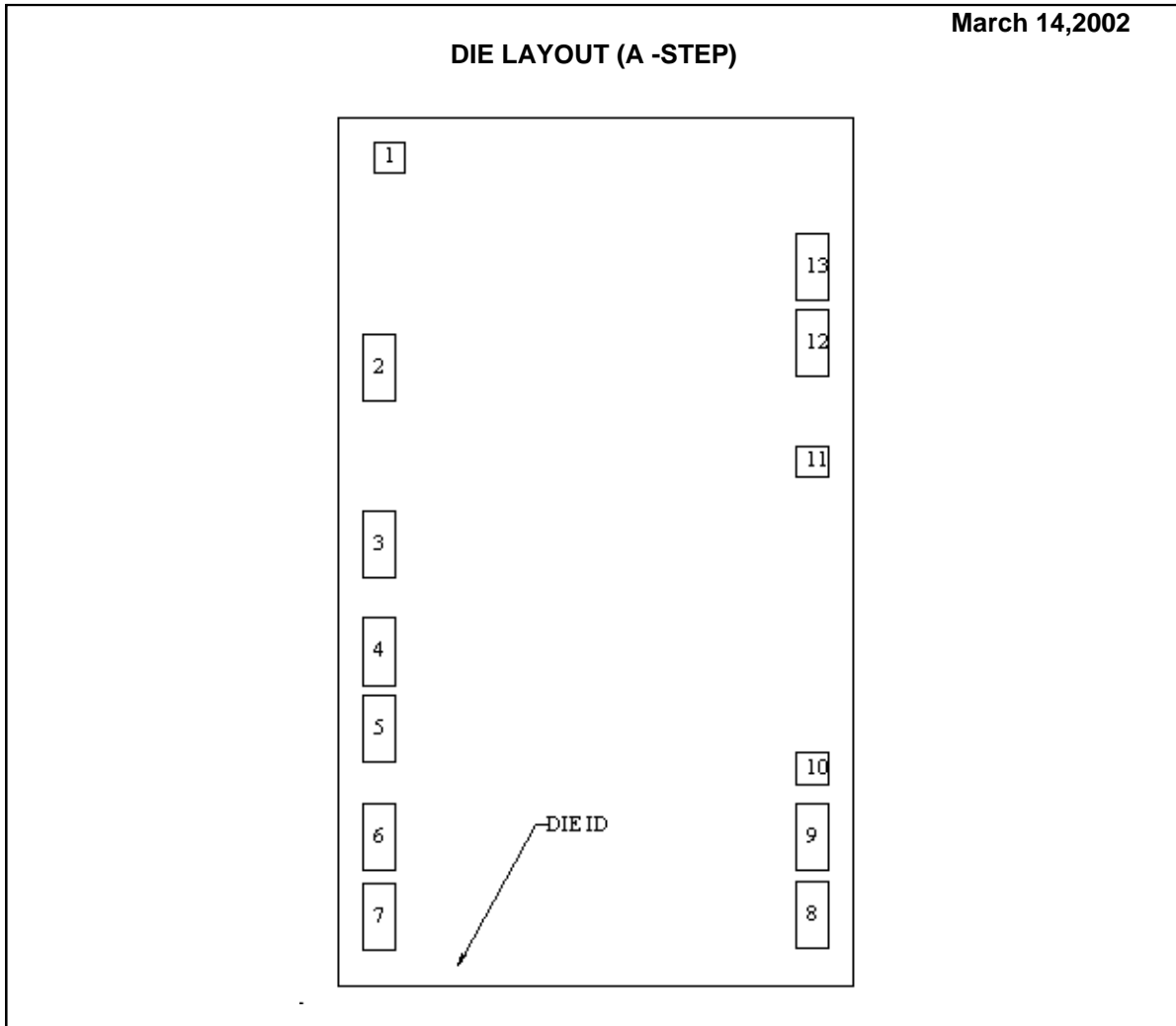


**LM2662 MDC MWC
SWITCHED CAPACITOR VOLTAGE CONVERTER**



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM2662A	Bond Pad Opening Size (min)	112 μ m x 112 μ m
Die Step	A	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	3048 μ m x 1803 μ m 120mils x 71mils	Back Side Connection	Floating
Thickness	406 μ m Nominal		
Min Pitch	239 μ m Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (A -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection						
SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES		PAD SIZE		
		X	Y	X	Y	
FC	1	-724	1384	112	x	112
CAP+	2	-761	648	112	x	234
CAP+	3	-761	25	112	x	234
GND	4	-761	-350	112	x	234
GND	5	-761	-621	112	x	234
CAP-	6	-761	-1003	112	x	234
CAP-	7	-761	-1279	112	x	234
OUT	8	761	-1275	112	x	234
OUT	9	761	-999	112	x	234
LV	10	761	-759	112	x	112
ODS	11	761	317	112	x	112
V+	12	761	731	112	x	234
V+	13	761	1001	112	x	234

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